

2.4W LMT2608 80.0:1 Transformer

DESCRIPTION

This document describes and specifies the electrical and mechanical characteristics of the SGE2690-1G high voltage transformer for CCFL inverter power supplies. SGE2690-1G is the RoHS compliant and Lead free transformer. For Reliability and Safety Specification, refer to SGE2606-4.

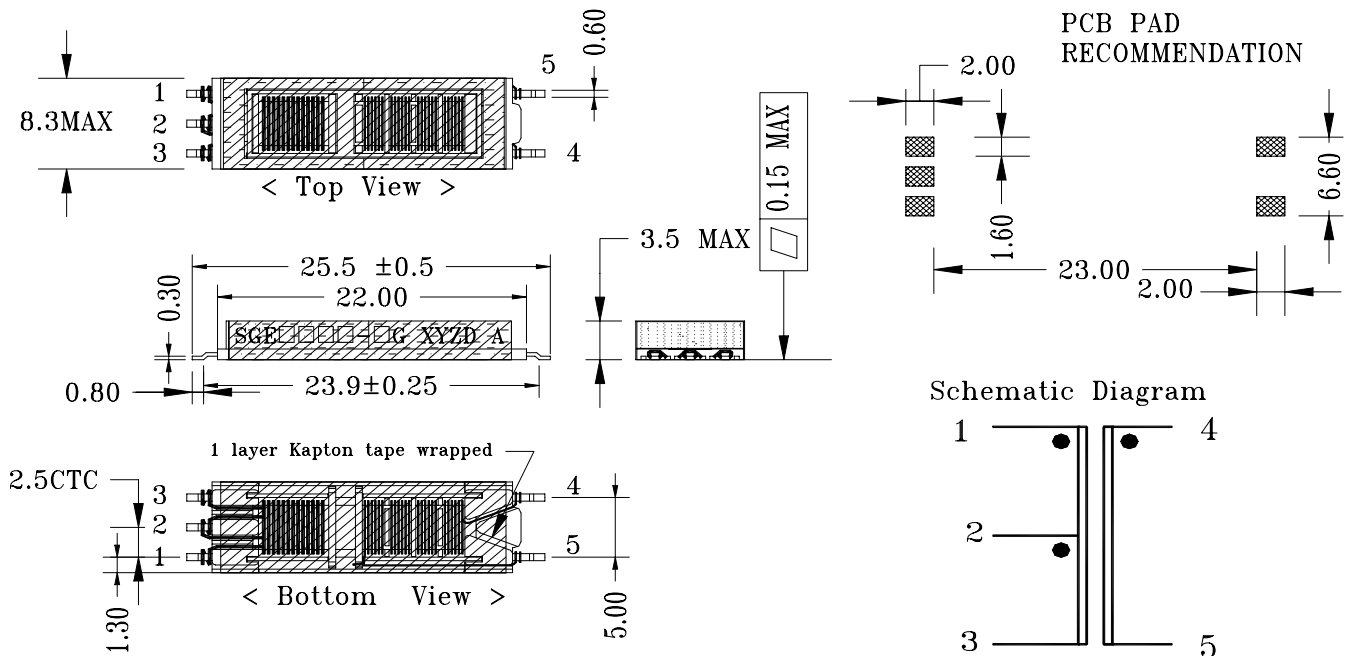
ELECTRICAL CHARACTERISTICS

Items	Inductance (@ 10KHz, 0.1V)			Items	DC. Resistance		
	Min	Nom	Max		Min	Nom	Max
L1-2, L2-3 (μH)	13.8	17	21.8	R _{DC} 1-2, R _{DC} 2-3(mΩ)	87	95	102
L4-5 (mH)	310	426	537	R _{DC} 4-5 (Ω)	470	490	510
L _{LKG1-2} , L _{LKG2-3} (μH)	Inductance (@ 100KHz, 1V)			R _{DC} 1-2 / R _{DC} 2-3	0.96	1	1.04
	3.6	4.1	4.6				
L _{LKG4-5} (mH)	NA	NA	NA	Secondary Self Capacitance (HP4192A 1MHz C meter, 30mVrms)			
				C _{4.5} (pF)	1.5	2.5	3.5
Rating				Dielectric Voltage Withstand			
Note: Max output power varies depend on operating condition.				60Hz, Arc-detect enabled, 5 sec. min. 200μA max. leakage current			
Max Open Output Voltage	1200V _{RMS} , 3sec.			Secondary to Core	1500V _{RMS} min. (60sec)		
Max Output Voltage	850V _{RMS}			Primary to Core	750V _{RMS} min.		
Max Output Power	2.4W			Primary to Secondary	750V _{RMS} min.		

WINDING SPECIFICATIONS

	Primary		Secondary
	Pin 1 – 2	Pin 2 – 3	Pin 4 – 5
Winding Sequence	1S – 2F	2S – 3F	4S – 5F
Wire Size & Type	0.23φ, Single Insulation, 180°C	0.23φ, Single Insulation, 180°C	0.03φ, Triple Insulation, 180°C
Number of Turns	10	10	1600
Winding Method	Bifilar		

PHYSICAL SPECIFICATIONS & WIRING DIAGRAM



Note : This transformer is design for single ended application. Pin 5 must to be connected to low voltage side or ground.

PART MARKING

SGE□□□□-□G XYZD A – SGE2690-1G: MSC PN, XYZ: Datecode (X:YR, YZ=WK), D: Plant Code, A: Rev.#

PACKAGING SPEC AND ORDER INFORMATION

Packaging Order Information – SGE2690-1GTR (Tape and Reel)

TAPE & REEL : Refer to SGE2604-4 specification



Microsemi[®]

Specification Number
SGE2690-1G
Revision. A (090605)

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NOTES

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